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October 2010

74AUP1T97 TinyLogic[®] Low Power Configurable Gate with Voltage-Level Translator

Features

- Single Supply Voltage Translator
 - 1.8V to 3.3V Input at V_{CC} =3.3V
 - 1.8V to 2.5V Input at V_{CC}=2.5V
- 2.3V to 3.6V V_{CC} Supply Voltage Operation
- 3.6V Over-Voltage Tolerant I/O's at V_{CC} from 2.3V to 3.6V
- Power-Off High-Impedance Inputs and Outputs
- Low Static Power Consumption
 - I_{CC}=0.9µA Maximum
- Low Dynamic Power Consumption
 - C_{PD}=2.7pF Typical at 3.3V
- Ultra-Small MicroPak[™] Packages

Description

The 74AUP1T97 is a universal configurable 2-input logic gate that provides single supply voltage level translation. This device is designed for applications with inputs switching levels that accept 1.8V low voltage CMOS signals while operating from either a single 2.5V or 3.3V supply voltage. The 74AUP1T97 is an ideal low power solution for mixed voltage signal applications especially for battery-powered portable applications. This product guarantees very low static and dynamic power consumption across entire voltage range. All inputs are implemented with hysteresis to allow for slower transition input signals and better switching noise immunity.

The 74AUP1T97 provides for multiple functions as determined by various configurations of the three inputs. The potential logic functions provided are MUX, AND, NAND, OR, and NOR, inverter and buffer. Refer to Figures 3 to 9.

Ordering Information

Part Number	Top Mark	Package	Packing Method
74AUP1T97L6X	АН	6-Lead MicroPak™, 1.0mm Wide	5000 Units on Tape & Reel
74AUP1T97FHX	АН	6-Lead, MicroPak2™, 1x1mm Body, .35mm Pitch	5000 Units on Tape & Reel

Logic Diagram

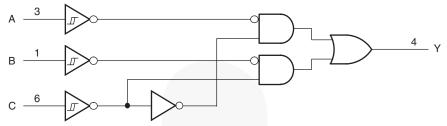


Figure 1. Logic Diagram (Positive Logic)

Pin Configurations

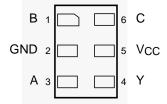


Figure 2. MicroPak™ (Top Through View)

Pin Definitions

Pin #	Name	Description
1	В	Data Input
2	GND	Ground
3	А	Data Input
4	Y	Output
5	V _{CC}	Supply Voltage
6	С	Data Input

Function Table

	Inputs		74AUPIT97
С	В	Α	Y=Output
L	L	L	L
L	L	Н	L
L	Н	L	Н
L	Н	Н	Н
Н	L	L	L
Н	L	Н	Н
Н	Н	L	L
Н	Н	Н	Н

H = HIGH Logic Level L = LOW Logic Level

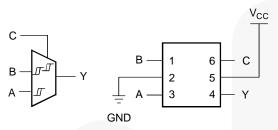
Function Selection Table

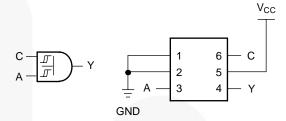
Logic Function	Connection Configuration		
2-to-1 MUX	Figure 3		
2-Input AND Gate	Figure 4		
2-Input OR Gate with One Inverted Input	Figure 5		
2-Input NAND Gate with One Inverted Input	Figure 5		
2-Input AND Gate with One Inverted Input	Figure 6		
2-Input NOR Gate with One Inverted Input	Figure 6		
2-Input OR Gate	Figure 7		
Inverter	Figure 8		
Buffer	Figure 9		

74AUP1T97 Logic Configurations

Figure 3 through Figure 9 show the logical functions that can be implemented using the 74AUP1T97. The diagrams show the DeMorgan's equivalent logic duals for a given two-input function. The logical

implementation is next to the board-level physical implementation of how the pins of the function should be connected.



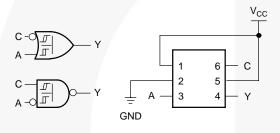


Note:

- 1. When C is L, Y=B.
- 2. When C is H, Y=A.

Figure 3. 2-to-1 MUX

Figure 4. 2-Input AND Gate



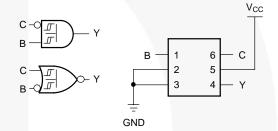


Figure 5. Input OR Gate with One Inverted Input
2-Input NAND Gate with One Inverted Input

Figure 6. 2-Input AND Gate with One Inverted Input 2-Input NOR Gate with One Inverted Input

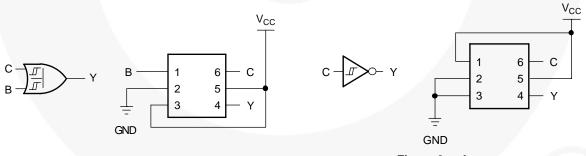


Figure 7. 2-Input OR Gate

Figure 8. Inverter

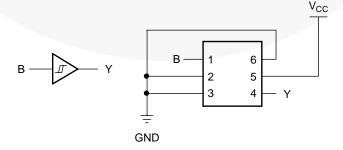


Figure 9. Buffer

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Para	ameter	Min.	Max.	Unit
V _{CC}	Supply Voltage		-0.5	4.6	V
V _{IN}	DC Input Voltage		-0.5	4.6	V
V	DC Output Voltage	HIGH or LOW State ⁽³⁾	-0.5	V _{CC} + 0.5	V
V _{OUT}	1 3	V _{CC} =0V	-0.5	4.6	V
I _{IK}	DC Input Diode Current	V _{IN} < 0V		-50	mA
	DC Output Diada Current	V _{OUT} < 0V		-50	~ ^
l _{OK}	DC Output Diode Current	$V_{OUT} > V_{CC}$		+50	mA
I _{OH} / I _{OL}	DC Output Source / Sink Curre		±50	mA	
Io	Continuous Output Current	Continuous Output Current			mA
Icc or I _{GND}	DC V _{CC} or Ground Current per	Supply Pin		±50	mA
T _{STG}	Storage Temperature Range		-65	+150	°C
T_J	Junction Temperature Under E	Bias		+150	°C
TL	Junction Lead Temperature, S	oldering 10s		+260	°C
В	Power Dissipation at +85°C	MicroPak-6		130	mW
P_D	Fower Dissipation at +65 C	MicroPak2-6		120	IIIVV
ESD	Human Body Model, JEDEC:J		5000+	V	
E2D	Charged Device Model, JEDE	C:JESD22-C101		2000	V

Note:

Recommended Operating Conditions⁽⁴⁾

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Conditions	Min.	Max.	Unit
V _{CC}	Supply Voltage		2.3	3.6	V
V _{IN}	Input Voltage		0	3.6	V
V	Output Voltage	V _{CC} =0V	0	3.6	V
V _{OUT}	Output Voltage	HIGH or LOW State	0	Vcc	V
1/1	Output Current	V _{CC} =3.0V to 3.6V		±4.0	mA
I _{OH} /I _{OL}	V _{CC} =2.3V to 2.7V	V _{CC} =2.3V to 2.7V		±3.1	IIIA
T _A	Operating Temperature, Free Air		-40	+85	°C
0	Thermal Resistance	MicroPak-6		500	°C/W
$\theta_{\sf JA}$	THEITIAI NESISIAIICE	MicroPak2-6		560	C/VV

Note:

4. Unused inputs must be held HIGH or LOW. They may not float.

^{3.} Io absolute maximum rating must be observed.

DC Electrical Characteristics

	5	.,	0 111	T _A =+	-25°C	T _A =-40 1	to +85°C			
Symbol	Parameter	V _{cc}	Conditions	Min.	Max.	Min.	Max.	Units		
	Positive Threshold	2.3V to 2.7V		0.60	1.10	0.60	1.10			
V _P	Voltage	3.0V to 3.6V		0.75	1.16	0.75	1.19	V		
	Negative	2.3V to 2.7V		0.35	0.60	0.35	0.60	V		
V _N	Threshold Voltage	3.0V to 3.6V		0.50	0.85	0.50	0.85	7 V		
\/	Lhustarasia Valtara	2.3V to 2.7V		0.23	0.60	0.10	0.60	V		
V _H	Hysteresis Voltage	3.0V to 3.6V		0.25	0.56	0.15	0.56	7 °		
		$2.3 \text{V} \leq \text{V}_{CC} \leq 3.6 \text{V}$	I _{OH} =-20μA	V _{CC} -0.1		V _{CC} -0.1				
		0.01/	I _{OH} =-2.3mA	2.05		1.97				
V_{OH}	HIGH Level Output Voltage	2.3V	I _{OH} =-3.1mA	1.90		1.85		V		
	Voltage	0.01/	I _{OH} =-2.7mA	2.72		2.67				
		3.0V	I _{OH} =-4mA	2.60		2.55				
	/	$2.3 \text{V} \leq \text{V}_{\text{CC}} \leq 3.6 \text{V}$	I _{OL} =20μA		0.10		0.10			
	LOW Level Output Voltage		0.01/	I _{OL} =2.3mA		0.31		0.33	V	
V _{OL}			2.3V	I _{OL} =3.1mA		0.44		0.45		
			voltage	voltago	renage	0.01/	I _{OL} =2.7mA		0.31	
		3.0V	I _{OL} =4.0mA		0.44	\	0.45			
I _{IN}	Input Leakage Current	0V to 3.6V	$0 \le V_{IN} \le 3.6$		±0.10		±0.50	μA		
l _{OFF}	Power Off Leakage Current	0V	$0 \leq \left(V_{IN}, V_O\right) \leq 3.6$		0.10		0.50	μA		
Δl_{OFF}	Additional Power Off Leakage Current	0V to 0.2V	V _{IN} or V _O =0V to 3.6V		0.20		0.60	μА		
	Quiescent Supply	2 2 4 4 2 2 4	V _{IN} =V _{CC} or GND		0.50		0.90			
I _{CC}	Current	2.3V to 3.6V	$V_{CC} \le V_{IN} \le 3.6V$				±0.90	μA		
\.	Increase in I _{CC} per	2.3V to 2.7V	One Input at 0.3V or 1.1V, other Inputs at 0 or V _{CC}				4			
Δl _{CC}	Input	3.0V to 3.6V	One Input at 0.45V or 1.2V, other Inputs at 0 or V _{CC}				12	μΑ		

AC Electrical Characteristics

Symbol	Parameter	V	Conditions	T _A =+25°C		T _A =-40 to +85°C		Units	Figure	
Symbol	Parameter	V _{cc}	Conditions	Min.	Тур.	Max.	Тур.	Max.	Units	rigure
	$2.30V \le V_{CC} \le 2.70V$, $V_{IN}=1.65V$ to $1.95V$		1.1	3.7	5.5	1.1	6.8			
		2.30V ≤ V _{CC} ≤ 2.70V, V _{IN} =2.30V to 2.70V		1.1	3.8	6.5	1.1	7.0	İ	
		$2.30V \le V_{CC} \le 2.70V$, $V_{IN}=3.0V$ to $3.60V$	C _L =5pF,	1.1	3.9	6.0	1.1	6.5		
		$3.00V \le V_{CC} \le 3.60V$, $V_{IN}=1.65V$ to 1.95V	$R_L=1M\Omega$	1.0	3.3	4.9	1.0	8.0		
		$3.00V \le V_{CC} \le 3.60V,$ $V_{IN}=2.30V$ to 2.70V		1.0	3.2	4.6	1.0	5.8		
		$\begin{array}{c} 3.00 \text{V} \leq \text{V}_{CC} \leq 3.60 \text{V}, \\ \text{V}_{\text{IN}} = 3.00 \text{V to } 3.60 \text{V} \end{array}$		1.0	3.1	4.7	1.0	5.5		
		$2.30V \le V_{CC} \le 2.70V$, $V_{IN}=1.65V$ to $1.95V$		1.3	4.1	6.5	1.0	7.9		
		$ \begin{array}{c} 2.30 \text{V} \leq \text{V}_{\text{CC}} \leq 2.70 \text{V}, \\ \text{V}_{\text{IN}} = 2.30 \text{V to } 2.70 \text{V} \end{array} $		1.3	4.0	6.2	1.0	7.1		
		$2.30V \le V_{CC} \le 2.70V$, $V_{IN}=3.0V$ to $3.60V$	C _L =10pF,	1.3	3.7	5.7	1.0	6.5		
		$\begin{array}{c} 3.00 \text{V} \leq \text{V}_{CC} \leq 3.60 \text{V}, \\ \text{V}_{\text{IN}} = 1.65 \text{V to } 1.95 \text{V} \end{array}$	$R_L=1M\Omega$	1.3	3.5	5.6	1.0	8.5		
	7	$3.00V \le V_{CC} \le 3.60V$, $V_{IN}=2.30V$ to $2.70V$		1.3	3.4	5.3	1.0	6.1		
•	Propagation	$ \begin{array}{c} 3.00 \text{V} \leq \text{V}_{CC} \leq 3.60 \text{V}, \\ \text{V}_{\text{IN}} = 3.00 \text{V to } 3.60 \text{V} \end{array} $		1.3	3.3	5.2	1.0	5.9	ns	Figure 10 Figure 11
t _{PHL} , t _{PLH}	Delay	$2.30V \le V_{CC} \le 2.70V$, $V_{IN}=1.65V$ to $1.95V$		1.5	4.6	6.9	1.0	8.7		
		$ \begin{array}{c} 2.30 \text{V} \leq \text{V}_{\text{CC}} \leq 2.70 \text{V}, \\ \text{V}_{\text{IN}} = 2.30 \text{V to } 2.70 \text{V} \end{array} $		1.5	4.4	6.8	1.0	7.9		
		$2.30V \le V_{CC} \le 2.70V$, $V_{IN}=3.0V$ to $3.60V$	C _L =15pF,	1.5	4.2	6.3	1.0	7.4		
		$3.00V \le V_{CC} \le 3.60V$, $V_{IN}=1.65V$ to $1.95V$	R _L =1MΩ	1.3	3.9	6.2	1.0	9.1		
		$3.00V \le V_{CC} \le 3.60V$, $V_{IN}=2.30V$ to $2.70V$		1.3	3.8	5.6	1.0	6.8		
		$3.00V \le V_{CC} \le 3.60V$, $V_{IN}=3.00V$ to $3.60V$		1.3	3.8	5.6	1.0	6.2		
		$2.30V \le V_{CC} \le 2.70V$, $V_{IN}=1.65V$ to $1.95V$		1.3	4.2	7.9	1.3	8.5		
		$2.30V \le V_{CC} \le 2.70V$, $V_{IN}=2.30V$ to $2.70V$		1.3	3.9	7.9	1.3	8.5		
		$2.30V \le V_{CC} \le 2.70V$, $V_{IN}=3.0V$ to $3.60V$	C _L =30pF,	1.0	3.7	7.3	1.0	8.9		
	3	$3.00V \le V_{CC} \le 3.60V$, $V_{IN}=1.65V$ to $1.95V$	R _L =1MΩ	1.3	3.5	6.1	1.3	7.9		R
		$3.00V \le V_{CC} \le 3.60V$, $V_{IN}=2.30V$ to $2.70V$		1.1	3.0	5.9	1.1	6.8		
		$3.00V \le V_{CC} \le 3.60V$, $V_{IN}=3.00V$ to $3.60V$		1.0	2.7	5.7	1.0	6.5		
C _{IN}	Input Capacitance	0			2.1				pF	
C _{OUT}	Output Capacitance	0			3.0				pF	
C	Power Dissipation	$2.30 \text{V} \leq \text{V}_{\text{CC}} \leq 2.70 \text{V}$			2.0				nE.	
C_{PD}	Capacitance	$3.00V \le V_{CC} \le 3.60V$			2.7				pF	

AC Loadings and Waveforms

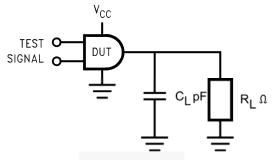


Figure 10. AC Test Circuit

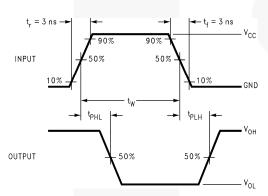
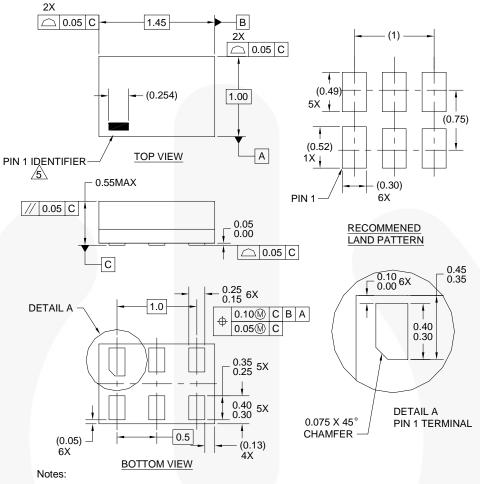


Figure 11. AC Waveforms

Symbol	V	сс
Symbol	3.3V ± 0.3V	2.5V ± 0.2V
V_{mi}	V _{IN} /2	V _{IN} /2
V_{mo}	V _{CC} /2	V _{CC} /2

Physical Dimensions



- 1. CONFORMS TO JEDEC STANDARD M0-252 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y14.5M-1994
- 4. FILENAME AND REVISION: MAC06AREV4
- 5. PIN ONE IDENTIFIER IS 2X LENGTH OF ANY
 - OTHER LINE IN THE MARK CODE LAYOUT.

Figure 12. 6-Lead, MicroPak™, 1.0mm Wide

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

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Tape and Reel Specifications

Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications: http://www.fairchildsemi.com/products/logic/pdf/micropak_tr.pdf.

Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
	Leader (Start End)	125 (Typical)	Empty	Sealed
L6X	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed

Physical Dimensions

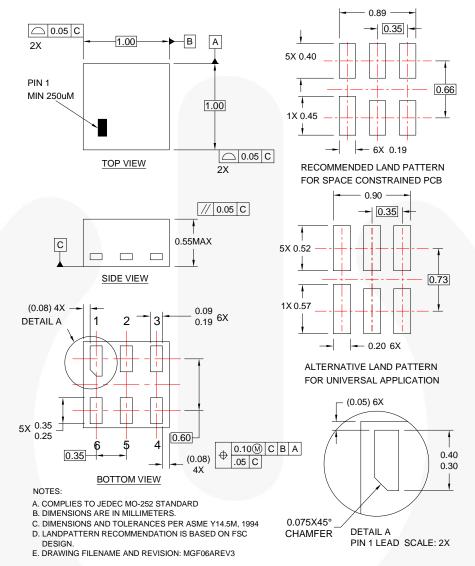


Figure 13. 6-Lead, MicroPak2™, 1x1mm Body, .35mm Pitch

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Tape and Reel Specifications

Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications: http://www.fairchildsemi.com/packaging/MicroPAK2_6L_tr.pdf.

Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
	Leader (Start End)	125 (Typical)	Empty	Sealed
FHX	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed





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SuperSOT™.8
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